



image

2811

**PATENT**  
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Serial No.: 09/812,276  
Filed: March 20, 2001  
Title: Semiconductor Device and Process  
of Production of Same  
Inventor(s): Michio Horiuchi et al.  
Examiner: Owens, Douglas W.  
Art Unit: 2811  
Atty. Dkt.: 072-01

**CERTIFICATE OF MAILING**

DATE OF DEPOSIT: **March 15, 2004**

I hereby certify that this correspondence is being deposited with the United States Postal Service in an envelope addressed to **Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450**, with sufficient postage for First Class Mail under 37 C.F.R. §1.8, on the date indicated above.

Name of person mailing paper or fee:

Ourmazd S. Ojan

Signature:

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**COVER LETTER WITH CERTIFICATE OF MAILING**

Dear Sir:

Enclosed and attached hereto are the following documents:

- (1) Cover Letter with Certificate of Mailing (1 pg.);
- (2) Summary of the Substance of the Interview ( 2 pgs.);
- (3) Paul & Paul postcard to be returned by PTO.

No fee is believed to be required with respect to this communication. In the event that fees are required, the Commissioner is hereby authorized to charge any additional fees, or credit any overpayment, to Paul & Paul Deposit Account No. 16-0750.

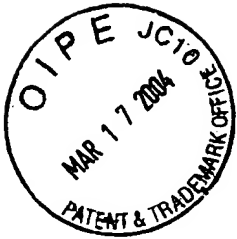
Respectfully submitted,

Ourmazd S. Ojan  
Reg. No. 38,065

Paul & Paul  
2900 Two Thousand Market Street  
Philadelphia, PA 19103  
(215) 568-4900

Date: March 15, 2004

Order No. 2153



**PATENT**

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Name of person  
mailing paper or fee: Ourmazd S. Ojan

Signature: 

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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**SUMMARY OF THE SUBSTANCE OF THE INTERVIEW**

Dear Sir:

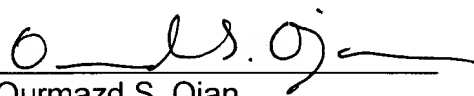
This communication is responsive to the Interview Summary form mailed on February 24, 2004, that set a one-month period for the applicant to provide a statement of the substance of the interview. The substance of the interview was summarized in our amendment and RCE filed on February 23, 2004, however, in an abundance of caution applicant provides herein a statement of the substance of the telephonic interview of February 12, 2004 with Examiner Owens.

During a Telephone interview with Examiner Owens on Thursday February 12, 2004, applicant's representative Mr. Ourmazd S. Ojan proposed to amend claim 20 by

incorporating the subject matter of claim 22 into claim 20 and further clarifying that the metal interconnections are formed in their entirety on the resin member. Applicant's representative argued that such an amendment should overcome the outstanding rejection because the applied art, in particular Takeda et al., did not disclose metal interconnections that are formed in their entirety on the resin member. The Examiner concurred that if claim 20 were amended as proposed, then the outstanding rejection would no longer apply. However, the examiner was of the opinion that a further search would be required. Accordingly, the Examiner could not agree that the proposed amendment would place the application in condition for allowance, and very likely the proposed amendment could not be entered after the final action.

Respectfully submitted,

March 15, 2004

  
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